



For more information, contact:
Dennis Scott, President
Questar Products International
925-461-0100
dennis@questarproducts.com

Fully automatic, fine-pitch machines offer unmatched affordability...

QUESTAR ENHANCES, STREAMLINES DESIGN OF AUTOMATIC WIRE BONDRERS FOR SUPERIOR PERFORMANCE, REDUCED PRICE POINT

PLEASANTON, Calif. –(March 24, 2011)– Questar Products International, a manufacturer of automatic wire bonders for the global assembly market, has further refined and enhanced the design of its fine-pitch, fine-wire (17 μ -75 μ), Al/Au automatic wedge and ball bonders to better meet the production challenges associated with smaller lot sizes, multiple product variations and frequent set-up changes. The new Q7000 Series has updated hardware and software, delivering a more tightly integrated assembly package, with approximately 30 percent fewer components and 50 percent less wiring than the Q2100 Series, which it replaces.

In addition, Questar has simplified the configuration selection process by including previously optional items, such as a programmable ultrasonic generator, as standard features. Also standard is ball/stud bumping, stitch bonding, and table tear for wedge bonding. Now, when ordering either the Q7700 or Q7800, the customer need only choose the appropriate heated

or ambient workholder and add a programmable temperature controller if gold wire is to be used with the Q7800 wedge bonder.

“The new Q7000 Series continues to offer the superior performance of the previous iteration, but with the improved manufacturing process, we can provide customers an even more durable product at a significantly better price point—about 10 percent less as compared to the Q2100 Series,” said Dennis Scott, president, Questar Products International.

QUESTAR INTRODUCES NEXT-GENERATION WIRE BONDERS, PG. 2

“No other wire bonder line offers a comparable combination of operator friendliness, flexibility, productivity, quality and low cost-of-ownership.”

These automatic wire bonders support a variety of customer needs from prototyping to medium-volume production. Designed for packaging applications from basic monolithic to complex hybrid devices and custom, specialty systems, the Q7000 series accommodates a multitude of device configurations. Package conversions are simple, fast and can be completed in minutes.

The new design has also placed all control electronics on the top of the bonders for easier, no-tools-required access.

“We’ve improved the infrastructure, pared down the parts, and tweaked the software, managing to lower the price and making our machines even more cost-efficient than they were before,” said Scott.

The Q7000 Series is designed with today’s demanding applications in mind. User-friendliness, higher small-lot productivity, very fine-pitch capability, and fast, accurate pattern recognition result in the bonders’ superior performance in its target marketplace.

Questar Products offers both hardware and software customization for specialty device applications such as unique wire-shaping and larger bondable area requirements.

Another advantage of the new machine design is that users will save on maintenance costs due to its virtually maintenance-free electronics. When service is needed, however, it can be accomplished quickly and efficiently with available remote diagnostics for the software and unrestricted access to the control components. Procurement of replacement parts is simplified

and much less expensive, as the machines are designed with off-the-shelf components available directly from suppliers worldwide.

Running on the Windows XP Pro™ operating system, the Q7000 Series offers intuitive, menu-driven software that is easy to program, with convenient access to all machine functions. The user-friendly operator interface provides point-and-click bonding; unlimited wires; easy bond process editing; extensive program storage; and a bond parameter library.

QUESTAR INTRODUCES NEXT-GENERATION WIRE BONDERS, PG. 3

For more information on the Q7000 Series, visit www.questarproducts.com.

About Questar

Since 1984, Questar has been providing wire-bonding machines to the global solid-state component assembly market. Today, Questar fine-pitch automatic wire bonders are cost-effective, flexible, easy-to-use, and delivered at a price-point that is unmatched by any other manufacturer. While other manufacturers focus on equipment with high-speed, high-volume capabilities, Questar is committed to supplying machines and support to customers with lower volume, smaller lots, high wire count and other special needs. For more information, please visit www.questarproducts.com or call 925-461-0100.

###